0.5A Low V_F Schottky Barrier Rectifier

RB0520LSH

Features

- High current capability, low forward voltage drop
- High surge current capability
- Low power loss, high efficiency
- High temperature soldering guaranteed, 250°C/10 seconds
- Low profile surface mounted package in order to minimize board space
- Pb-free lead plating and halogen-free package

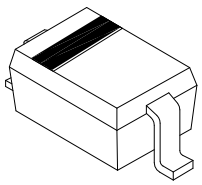
Mechanical data

- Case : Molded plastic, JEDEC SOD-123.
- Epoxy : UL94-V0 rated flame retardant
- Terminals : Plated terminals, solderable per MIL-STD-202 method 208
- Polarity : Indicated by cathode band
- Mounting position : Any
- Weight : approx. 0.04 gram

Symbol

RB0520LSH

Outline



2 (Anode)

SOD-123

Ordering Information

Device	Package	Shipping
RB0520LSH-0-T1-G	SOD-123 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel

Environment friendly grade : S for RoHS compliant products, G for RoHS compliant and green compound products

Packing spec, T1 : 3000 pcs / tape & reel, 7” reel

Product rank, zero for no rank products

Product name

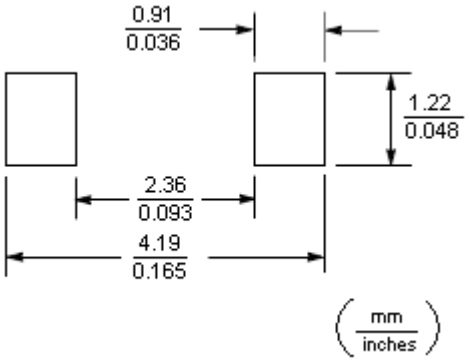
Absolute Maximum Ratings (T_A=25℃, unless otherwise noted)

Parameters	Conditions	Symbol	Min	Typ	Max	Units
Repetitive peak reverse voltage		V_{RRM}			20	V
RMS voltage		V_{RMS}			14	V
Continuous reverse voltage		V_R			20	V
Forward rectified current		I_O			0.5	A
Forward surge current	8.3ms single half sine-wave superimposed on rated load (JEDEC method)	I_{FSM}			10	A
Thermal resistance	Junction to Case	$R_{\theta JC}$		200		°C/W
	Junction to Ambient	$R_{\theta JA}$		250		
Storage temperature range		Tstg	-65		150	°C
Operating junction temperature range		Tj	-55		125	°C

Characteristics (T_A=25°C)

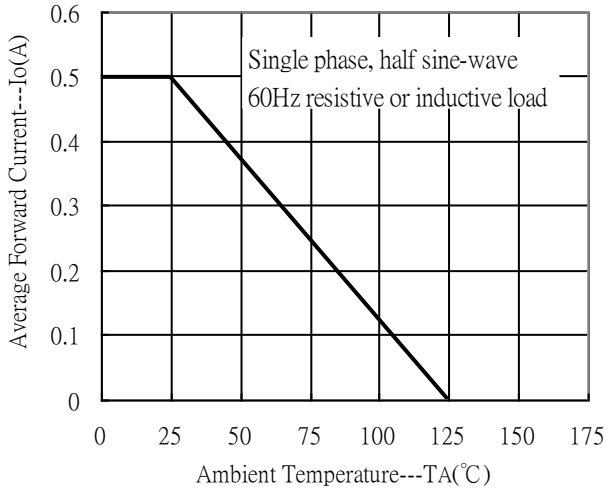
Characteristic	Symbol	Condition	Min.	Typ	Max.	Unit
	V_R	I_R=200μA	20	-	-	V
Forward Voltage	V_F 1	I_F=100mA	-	-	300	mV
	V_F 2	I_F=500mA	-	-	385	
Reverse Leakage Current	I_R 1	V_R=10V	-	-	100	μA
	I_R 2	V_R=20V	-	-	200	μA
Junction Capacitance	C_J	V_R=4V, f=1MHz	-	36	-	pF

Recommended Soldering Footprint

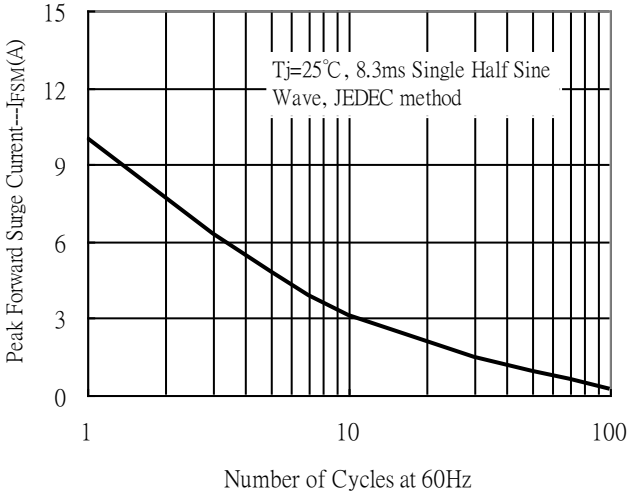


Typical Characteristics

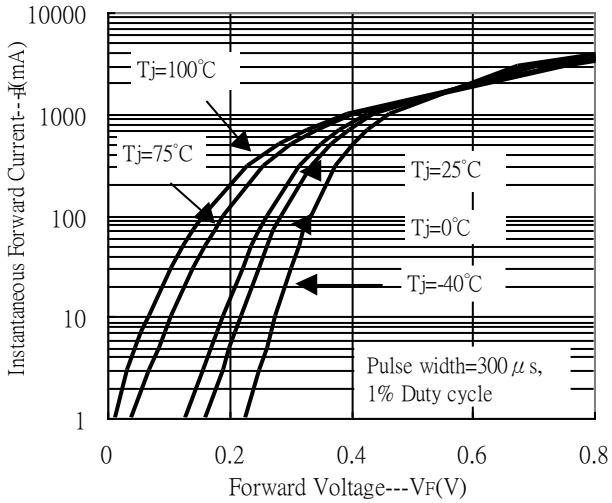
Forward Current Derating Curve



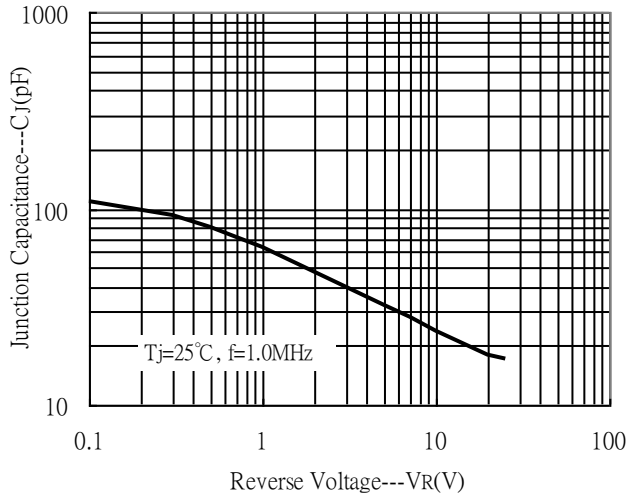
Maximum Non-Repetitive Forward Surge Current



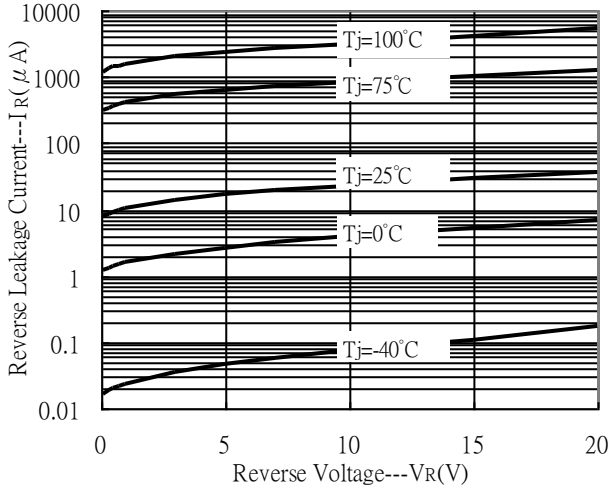
Forward Current vs Forward Voltage



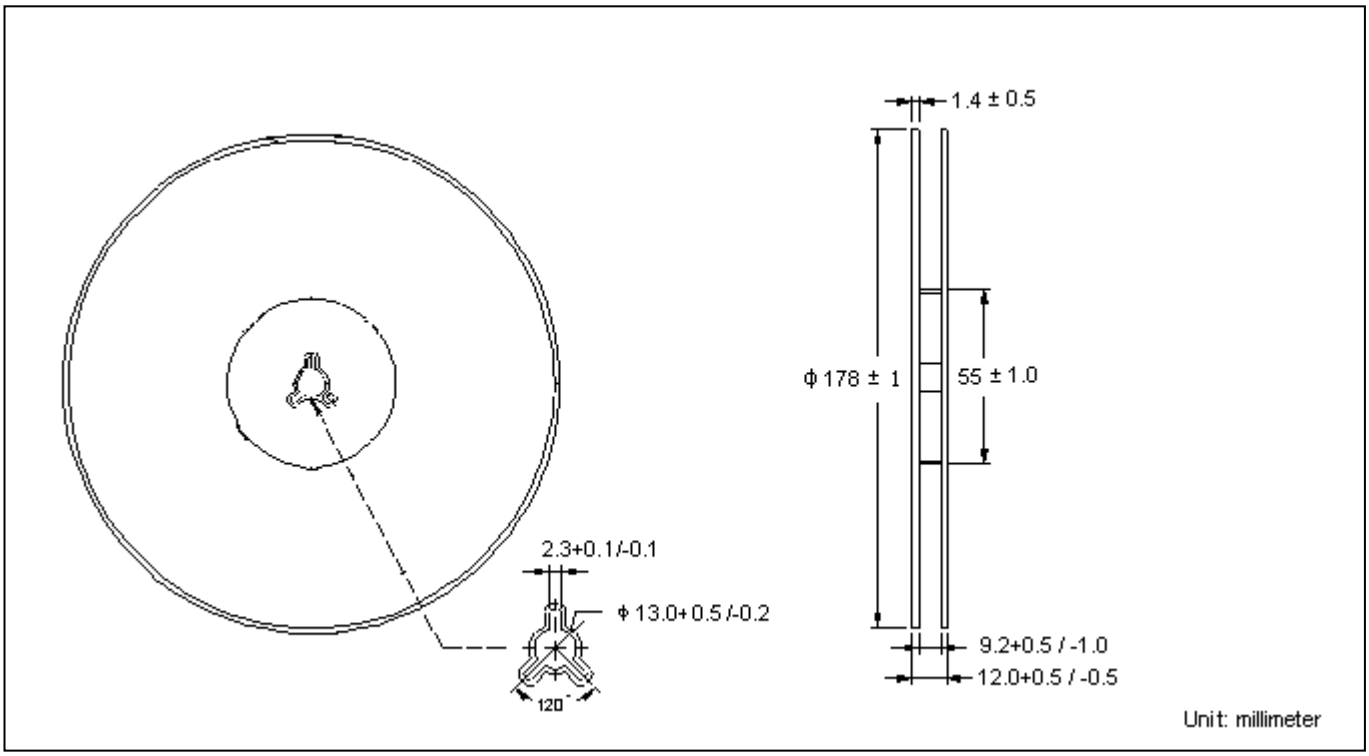
Junction Capacitance vs Reverse Voltage



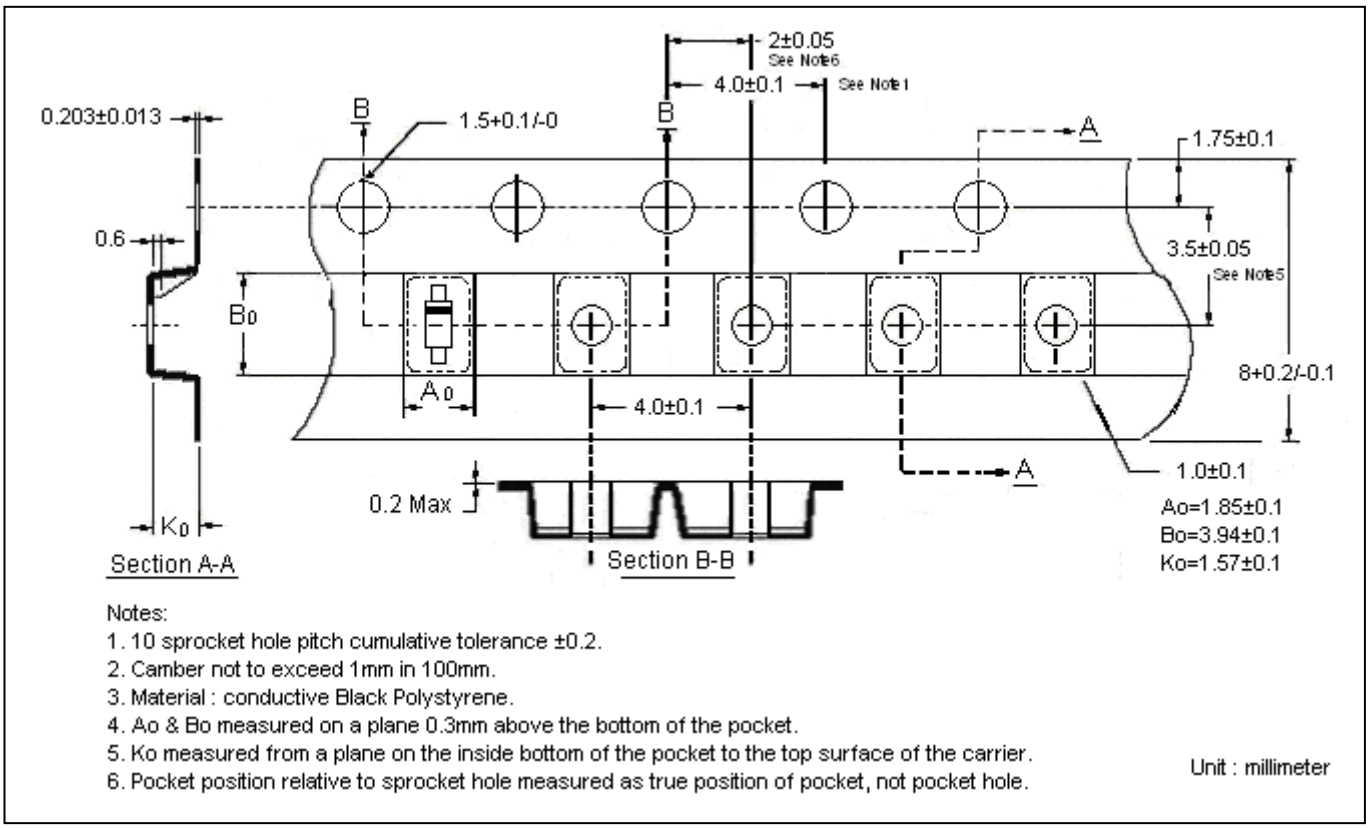
Reverse Leakage Current vs Reverse Voltage



Reel Dimension



Carrier Tape Dimension



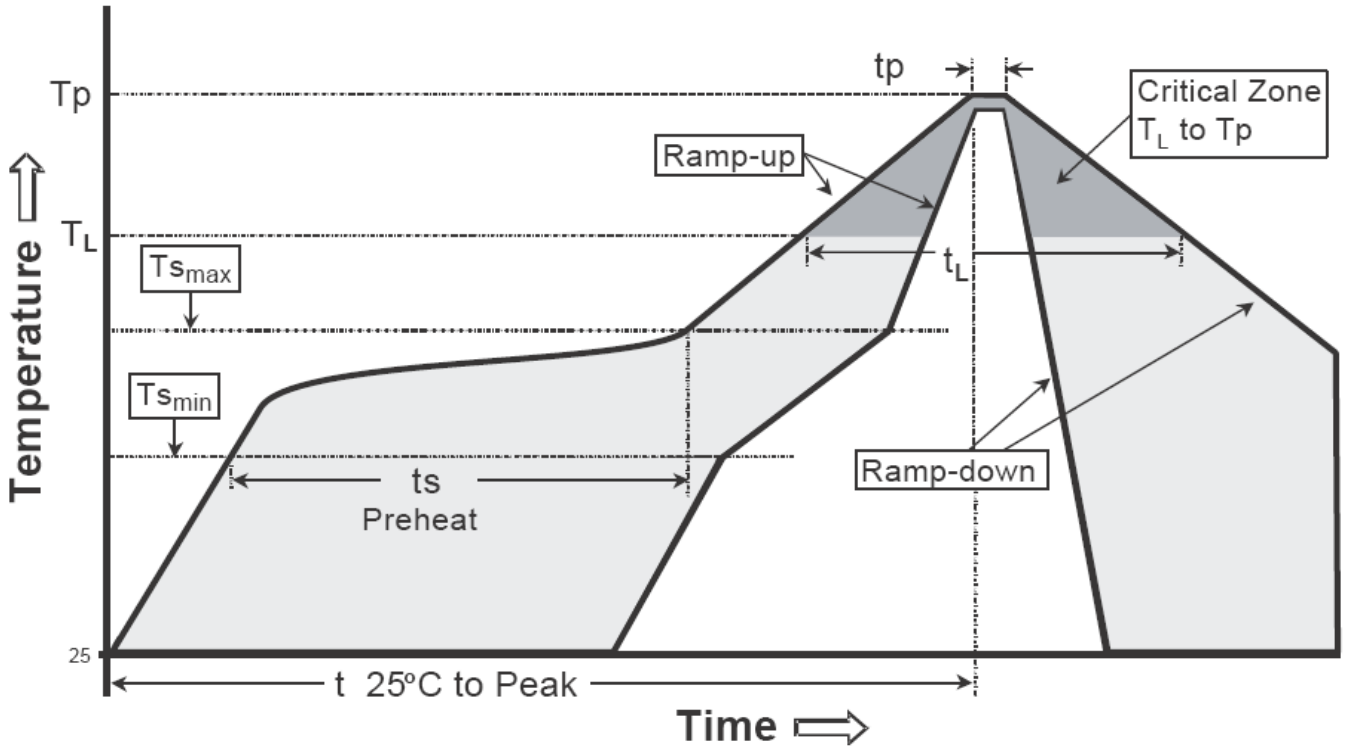
Notes:
1. 10 sprocket hole pitch cumulative tolerance ±0.2.
2. Camber not to exceed 1mm in 100mm.
3. Material : conductive Black Polystyrene.
4. Ao & Bo measured on a plane 0.3mm above the bottom of the pocket.
5. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.

Unit : millimeter

Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

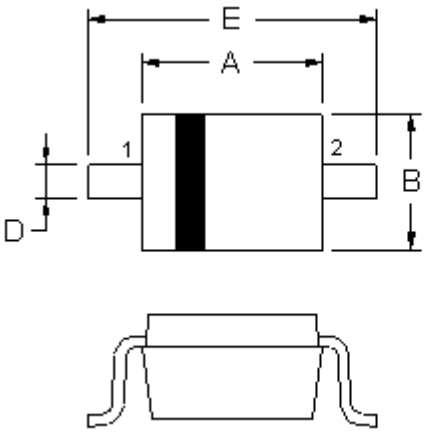
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat −Temperature Min(T_S min) −Temperature Max(T_S max) −Time(ts min to ts max)	 100°C 150°C 60-120 seconds	 150°C 200°C 60-180 seconds
Time maintained above: −Temperature (T_L) − Time (t_L)	 183°C 60-150 seconds	 217°C 60-150 seconds
Peak Temperature(T_P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOD-123 Dimension



Marking:

2-Lead SOD-123 Plastic
Surface Mounted Package
CYStek Package Code: SH

Style: Pin 1.Cathode 2.Anode

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.102	0.110	2.600	2.800	D	0.018	0.026	0.450	0.650
B	0.059	0.067	1.500	1.700	E	0.140	0.152	3.550	3.850
C	0.041	0.049	1.050	1.250					

Notes: 1.Controlling dimension : millimeters.
2.Lead thickness specified per L/F drawing with solder plating.
3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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